SN54LVC257A, SN74LVC257A
ZHCSWC2Q – JANUARY 1993 – REVISED DECEMBER 2024

SNx4LVC257A 具有三态输出的四通道 2 线至 1 线数据选择器和多路复用器

1 特性

- 工作电压范围为 1.65V 至 3.6V
- 输入电压高达 5.5V
- 3.3V 时，t_{pd} 最大值为 4.6ns
- V_{OLP}（输出接地反弹）典型值 <0.8V（V_{CC} = 3.3V、T_A = 25°C）
- V_{OHV}（输出 V_{OH} 下冲）典型值 >2V（V_{CC} = 3.3V、T_A = 25°C）
- 闩锁性能超过 250mA，符合 JESD 17 规范
- ESD 保护性能超过 JESD 22 规范要求
  - 2000V 人体放电模型 (A114-A)
  - 200V 机器放电模型 (A115-A)
- 对于符合 MIL-PRF-38535 标准的产品，所有参数均经过测试，除非另有说明。对于所有其他产品，生产流程不一定包含对所有参数的测试。

2 应用

- 线缆调制解调器终端系统
- 测试和测量
- I/O 扩展器
- 电机驱动器
- 网络交换机
- 服务器
- 电信基础设施

3 说明

这些四通道 2 线至 1 线数据选择器和多路复用器可在 1.65V 至 3.6V V_{CC} 下运行。

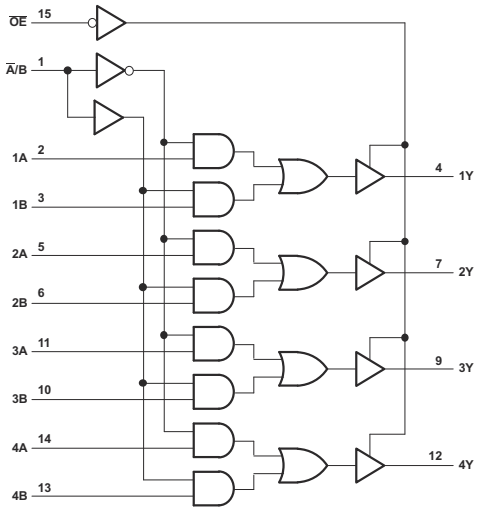
SNx4LVC257A 器件旨在将 4 位数据源的信号多路复用到总线式系统中的 4 路输出数据线。当输出使能 ($\overline{OE}$) 输入处于高逻辑电平时，三态输出不会为数据线施加负载。

输入可以由 3.3V 或 5V 器件驱动。此功能允许在 3.3V 或 5V 的混合系统环境中将此类器件用作转换器。

器件信息

器件型号	封装(1)	封装尺寸(2)	本体尺寸(3)
SNx4LVC257A	BQB（WQFN，16）	3.5mm × 2.5mm	3.5mm × 2.5mm
	D（SOIC，16）	9.90mm × 6mm	9.90mm × 3.90mm
	DB（SSOP，16）	6.20mm × 7.8mm	6.20mm × 5.30mm
	NS（SOP，16）	5mm × 6.4mm	5mm × 4.4mm
	PW（TSSOP，16）	5.00mm × 6.4mm	5.00mm × 4.40mm
	RGY（VQFN，16）	4mm × 3.5mm	4mm × 3.5mm

(1) 如需了解更多信息，请参阅机械、封装和可订购信息。
(2) 封装尺寸（长 × 宽）为标称值，并包括引脚（如适用）。
(3) 本体尺寸（长 x 宽）为标称值，不包括引脚。



所示引脚编号用于 D、DB、J、NS、PW、RGY 和 W 封装。

逻辑图（正逻辑）

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4 Pin Configuration and Functions

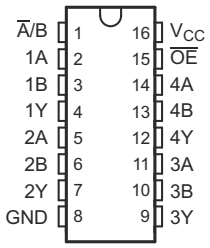


图 4-1. D, DB, NS, J, W, or PW Package; 16-Pin SOIC, SSOP, SO, CDIP, CFP, or TSSOP (Top View)

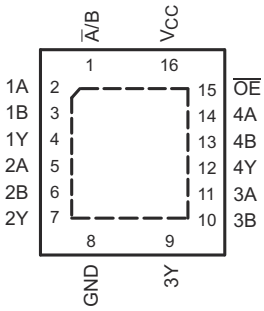


图 4-2. BQB or RGY Package; 16-Pin WQFN or VQFN with Exposed Thermal Pad (Top View)

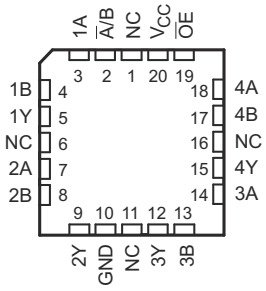


图 4-3. FK Package, 20-Pin LCCC Top View

PIN			I/O	DESCRIPTION
NAME	SOIC, SSOP, SO, CDIP, CFP, TSSOP, WQFN, or VQFN	LCCC		
$\overline{A}$/B	1	2	I	Select Pin, Low selects A, High selects B
1A	2	3	I/O	Multiplexer Signal Input
1B	3	4	I/O	Multiplexer Signal Input
1Y	4	5	I/O	Multiplexer Output
2A	5	7	I/O	Multiplexer Signal Input
2B	6	8	I/O	Multiplexer Signal Input
2Y	7	9	I/O	Multiplexer Output
3A	11	14	I/O	Multiplexer Signal Input
3B	10	13	I/O	Multiplexer Signal Input
3Y	9	12	I/O	Multiplexer Output
4A	14	18	I/O	Multiplexer Signal Input
4B	13	17	I/O	Multiplexer Signal Input
4Y	12	15	I/O	Multiplexer Output
GND	8	10	—	Ground
NC(1)	—	1, 6, 11, 16	—	No connect
$\overline{OE}$	15	19	I/O	Active low Output enable
V_{CC}	16	20	—	Power pin

(1) NC – no internal connection

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		–0.5	6.5	V
V_I	Input voltage(2)		–0.5	6.5	V
V_O	Output voltage(2) (3)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The value of V_{CC} is provided in the recommended operating conditions table.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

			SN54LVC257A		SN74LVC257A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	Operating	2	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V			0.65 × V_{CC}		V
		V_{CC} = 2.3 V to 2.7 V			1.7		
		V_{CC} = 2.7 V to 3.6 V	2		2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V				0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V				0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8		0.8	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65 V				–4	mA
		V_{CC} = 2.3 V				–8	
		V_{CC} = 2.7 V		–12		–12	
		V_{CC} = 3 V		–24		–24	
I_{OL}	Low-level output current	V_{CC} = 1.65 V				4	mA
		V_{CC} = 2.3 V				8	
		V_{CC} = 2.7 V		12		12	
		V_{CC} = 3 V		24		24	

over operating free-air temperature range (unless otherwise noted)(1)

		SN54LVC257A		SN74LVC257A		UNIT
		MIN	MAX	MIN	MAX	
Δt/Δv	Input transition rise or fall rate		10		10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, SCBA004.

5.4 Thermal Information

THERMAL METRIC(1)		SN74LVC257A						UNIT
		BQB (WQFN)	D (SOIC)	DB (SSOP)	NS (SO)	PW (TSSOP)	RGY (VQFN)	
		16 PINS						
$R_{\theta JA}$	Junction-to-ambient thermal resistance	98.8	118.1	82	64	141.8	87.1	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LVC257A			SN74LVC257A			UNIT
			MIN	TYP(1)	MAX	MIN	TYP(1)	MAX	
V_{OH}	I_{OH} = –100 µA	1.65 V to 3.6 V				V_{CC} – 0.2			V
	I_{OH} = –100 µA	2.7 V to 3.6 V	V_{CC} – 0.2						
	I_{OH} = –4 mA	1.65 V				1.2			
	I_{OH} = –8 mA	2.3 V				1.7			
	I_{OH} = –12 mA	2.7 V	2.2			2.2			
		3 V	2.4			2.4			
	I_{OH} = –24 mA	3 V	2.2			2.2			
V_{OL}	I_{OL} = 100 µA	1.65 V to 3.6 V						0.2	V
		2.7 V to 3.6 V			0.2				
	I_{OL} = 4 mA	1.65 V						0.45	
	I_{OL} = 8 mA	2.3 V						0.7	
	I_{OL} = 12 mA	2.7 V			0.4			0.4	
	I_{OL} = 24 mA	3 V			0.55			0.55	
I_I	V_I = 5.5 V or GND	3.6 V			±5			±5	µA
I_{OZ}	V_O = V_{CC} or GND	3.6 V			±15			±10	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	3.6 V			10			10	µA
ΔI_{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	2.7 V to 3.6 V			500			500	µA
C_i	V_I = V_{CC} or GND	3.3 V		5			5		pF
C_o	V_O = V_{CC} or GND	3.3 V		5			5		pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

5.6 Switching Characteristics, SN54LVC257A

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVC257A				UNIT
			V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		
			MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y		5.4	1	4.6	ns
	$\overline{A}$/B			7.5	1	6.4	
t_{en}	$\overline{OE}$	Y		6.7	1	5.6	ns
t_{dis}	$\overline{OE}$	Y		4.7	0.5	4.3	ns
$t_{sk(o)}$						1	ns

5.7 Switching Characteristics, SN74LVC257A

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74LVC257A								UNIT
			V_{CC} = 1.8 V ± 0.15 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	1	13.5	1	7.4	1	5.4	1	4.6	ns
	$\overline{A}$/B		1	15.6	1	9.5	1	7.5	1	6.4	
t_{en}	$\overline{OE}$	Y	1	14.6	1	8.7	1	6.7	1	5.6	ns
t_{dis}	$\overline{OE}$	Y	1	15.4	1	6.7	1	4.7	1	4.3	ns
$t_{sk(o)}$										1	ns

5.8 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC} = 1.8 V	V_{CC} = 2.5 V	V_{CC} = 3.3 V	UNIT
			TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	f = 10 MHz	13.5	14.5	15.5	pF

5.9 Typical Characteristics

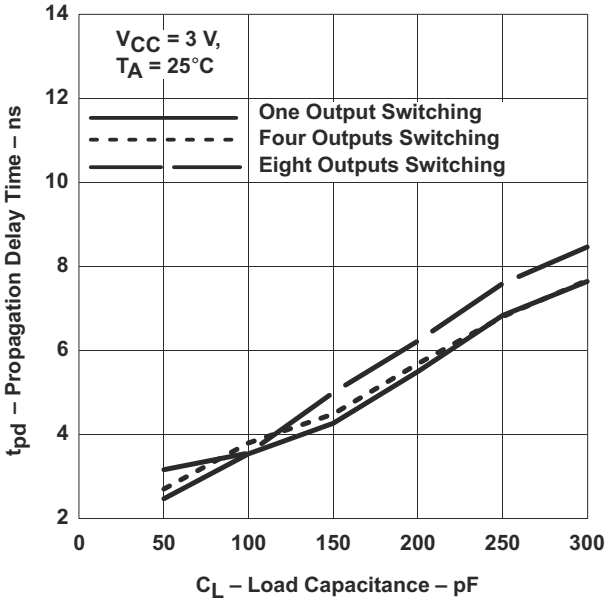


图 5-1. Propagation Delay (Low to High Transition) vs Load Capacitance

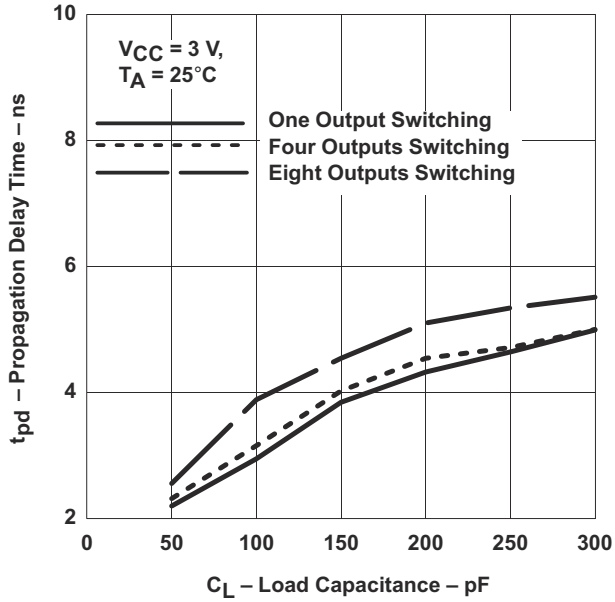
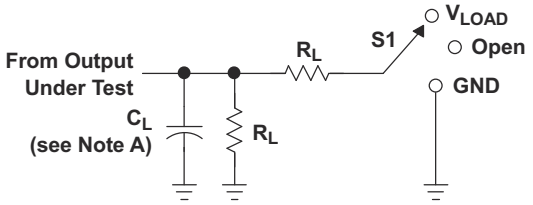


图 5-2. Propagation Delay (High to Low Transition) vs Load Capacitance

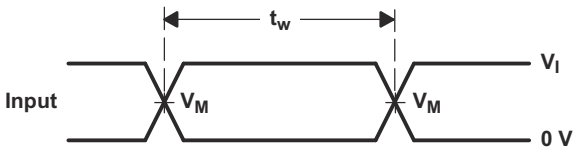
6 Parameter Measurement Information



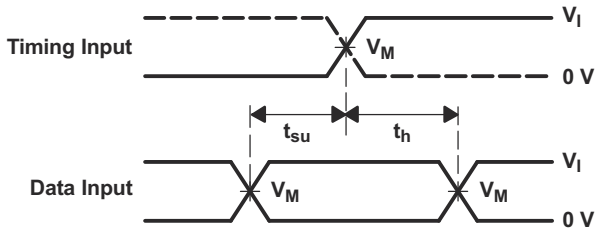
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

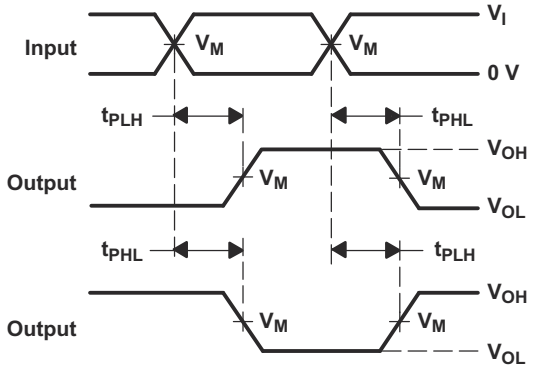
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
1.8 V±0.15 V	V_{CC}	≤2 ns	$V_{CC}/2$	2 × V_{CC}	30 pF	1 kΩ	0.15 V
2.5 V±0.2 V	V_{CC}	≤2 ns	$V_{CC}/2$	2 × V_{CC}	30 pF	500Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500Ω	0.3 V
3.3 V±0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500Ω	0.3 V



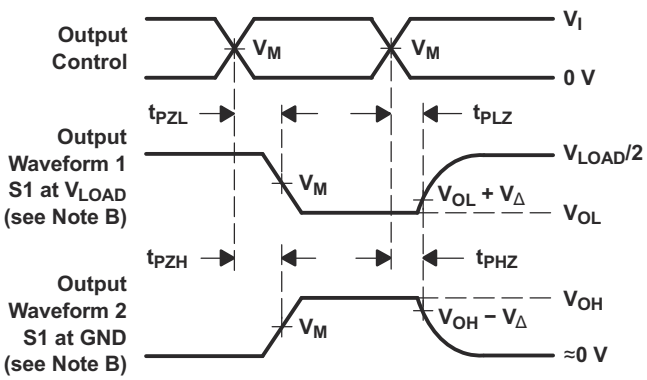
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤10 MHz, Z_O = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

图 6-1. Load Circuit and Voltage Waveforms

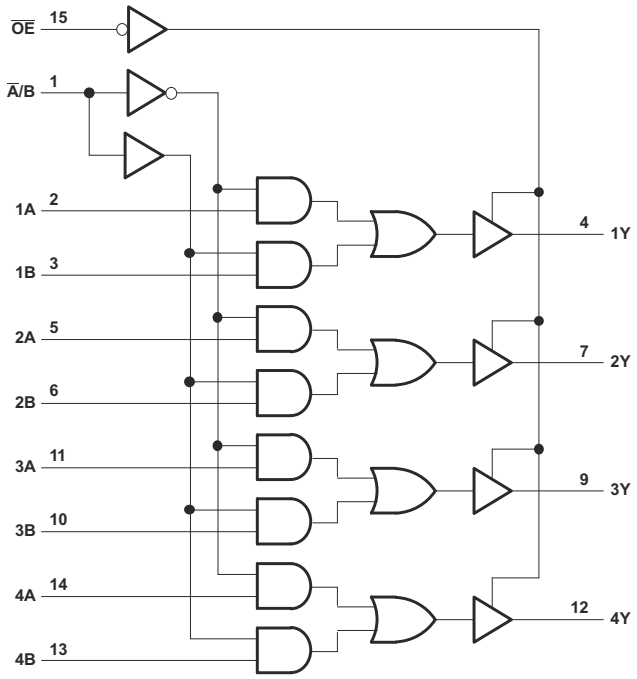
7 Detailed Description

7.1 Overview

These quadruple 2-line to 1-line data selectors and multiplexers are designed for 1.65-V to 3.6-V V_{CC} operation.

The SNx4LVC257A devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable ($\overline{OE}$) input is at a high logic level.

7.2 Functional Block Diagram



7.3 Feature Description

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V and 5-V system environment. Device features a maximum t_{pd} of 4.6 ns allowing the device to be used in high-speed applications as well.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ must be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

7.4 Device Functional Modes

表 7-1 lists the functional modes for the SN54LVC257A and SN74LVC257A devices.

表 7-1. Function Table

INPUTS				OUTPUT Y
$\overline{OE}$	$\overline{A}$/B	A	B	
H	X	X	X	Z
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

1 Application Information

The SNx4LVC257A devices are useful for digital signal data selector or multiplexer applications.

2 Typical Application

The SNx4LVC257A devices use CMOS technology and have balanced output drive. These devices can be used for down level translation and multiplexer function as shown in 图 8-1.

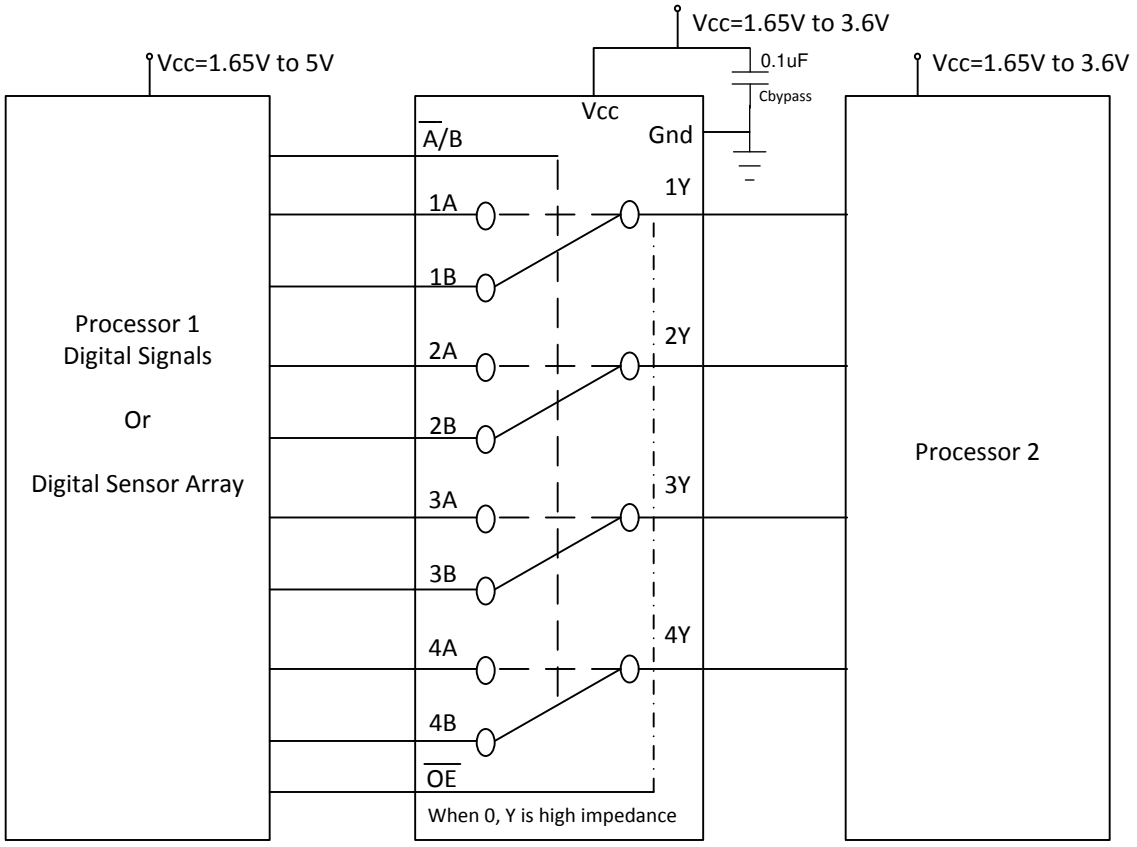


图 8-1. SNx4LVC257A Used as Level Translation and as a Multiplexer

2.1 Design Requirements

Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions must be considered to prevent ringing.

2.2 Detailed Design Procedure

1. Recommended Input Conditions
   - For rise time and fall time specification, see (Δt/ΔV) in the 节 5.3 table.
   - For specified high and low levels, see (V_{IH} and V_{IL}) in the 节 5.3 table.
   - Inputs are over voltage tolerant allowing them to go as high as (V_I max) in the 节 5.3 table at any valid V_{CC}.
2. Recommend Output Conditions
   - Load currents must not exceed (I_O max) per output and must not exceed (continuous current through V_{CC} or GND) total current for the part. These limits are in the 节 5.3 table.
   - Outputs must not be pulled above V_{CC}.

2.3 Application Curves

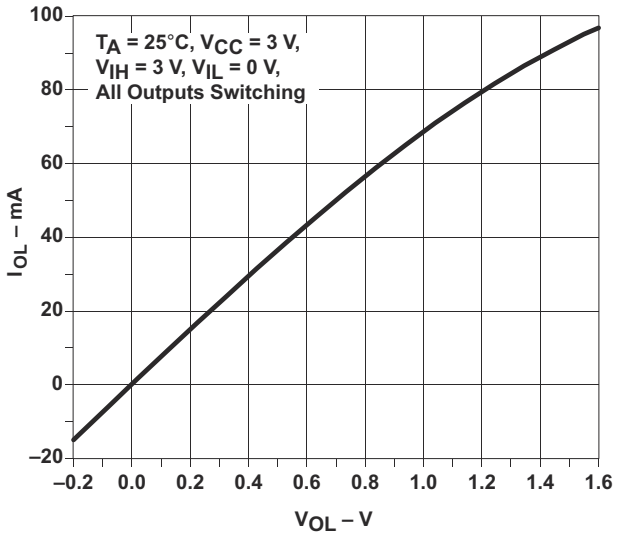


图 8-2. Output Drive Current (I_{OL}) vs LOW-level Output Voltage (V_{OL})

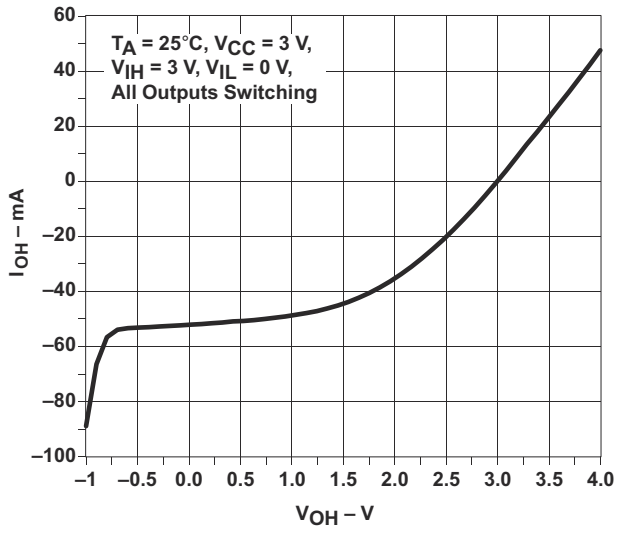


图 8-3. Output Drive Current (I_{OH}) vs HIGH-level Output Voltage (V_{OH})

3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the 节 5.3 table.

Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1-μF capacitor is recommended. If there are multiple V_{CC} terminals then 0.01-μF or 0.022-μF capacitors are recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. Multiple bypass capacitors may be paralleled to reject different frequencies of noise. The bypass capacitor must be installed as close to the power terminal as possible for the best results.

4 Layout

4.1 Layout Guidelines

When using multiple bit logic devices, inputs must not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in 图 8-4 are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that must be

applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC}, whichever makes more sense or is more convenient.

4.2 Layout Example

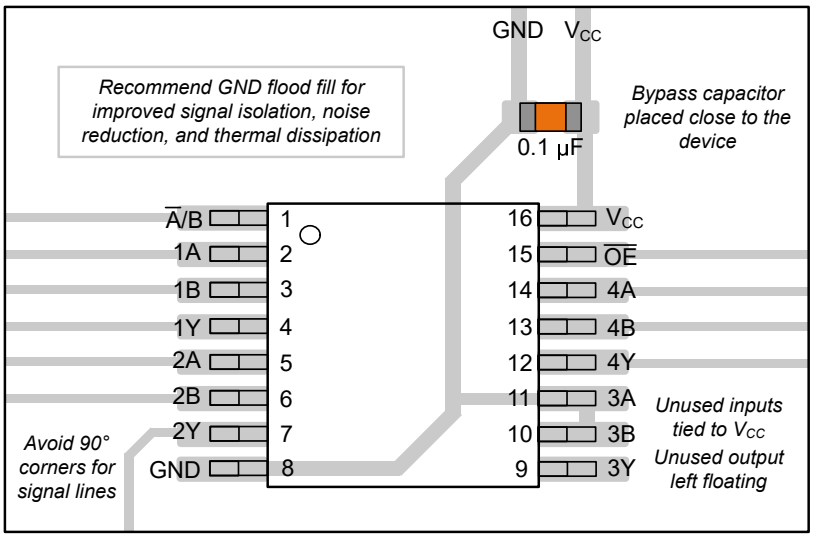


图 8-4. Example Layout for the SN74LVC257A

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Documentation

For related documentation see the following:

Implications of Slow or Floating CMOS Inputs, SCBA004

8.1.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54LVC257A	Click here	Click here	Click here	Click here	Click here
SN74LVC257A	Click here	Click here	Click here	Click here	Click here

8.2 Community Resources

8.3 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*通知* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.4 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

8.5 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

8.6 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.7 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision P (May 2024) to Revision Q (December 2024)	Page
• Updated RθJA values: D = 73 to 118.1, PW = 108 to 141.8, RGY = 39 to 87.1; Updated D, PW, and RGY packages for RθJC(top), RθJB, ΨJT, ΨJB, and RθJC(bot), all values in °C/W	5

Changes from Revision O (June 2015) to Revision P (May 2024) **Page**

- 向*封装信息*表、*引脚配置和功能*部分以及*热性能信息*表中添加了 BQA 封装 1
- 向*器件信息*表添加了封装尺寸并删除了*器件选项*表 1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-0050901QFA	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-0050901QF A SNJ54LVC257AW
SN74LVC257ABQBR	Active	Production	WQFN (BQB) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC257A
SN74LVC257ABQBR.A	Active	Production	WQFN (BQB) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LC257A
SN74LVC257AD	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257AD.B	Active	Production	SOIC (D) | 16	40 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257ADBR	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257ADBR.B	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257ADR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257ADR.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257ADR.B	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257ADRG4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257ANSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257ANSR.B	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC257A
SN74LVC257APW	Active	Production	TSSOP (PW) | 16	90 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APW.B	Active	Production	TSSOP (PW) | 16	90 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWR.B	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWRG4	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWRG4.B	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWT	Active	Production	TSSOP (PW) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257APWT.B	Active	Production	TSSOP (PW) | 16	250 | SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC257A
SN74LVC257ARGYR	Active	Production	VQFN (RGY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LC257A
SN74LVC257ARGYR.A	Active	Production	VQFN (RGY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LC257A
SN74LVC257ARGYR.B	Active	Production	VQFN (RGY) | 16	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LC257A
SNJ54LVC257AW	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-0050901QF A SNJ54LVC257AW

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF SN54LVC257A, SN74LVC257A :

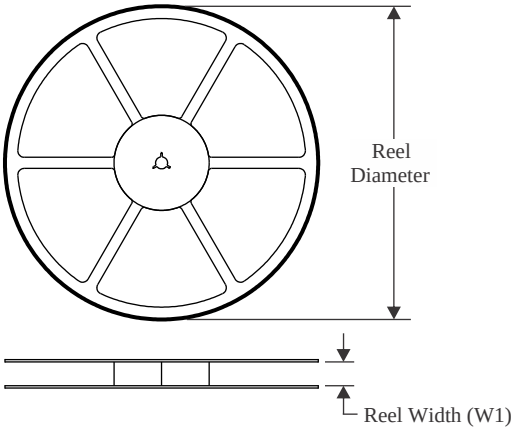
- Catalog : SN74LVC257A
- Automotive : SN74LVC257A-Q1, SN74LVC257A-Q1
- Enhanced Product : SN74LVC257A-EP, SN74LVC257A-EP
- Military : SN54LVC257A

NOTE: Qualified Version Definitions:

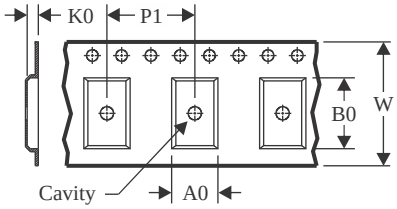
- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

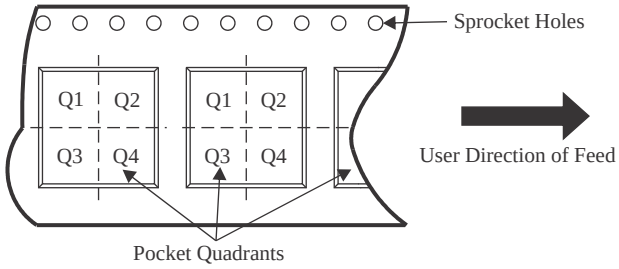


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

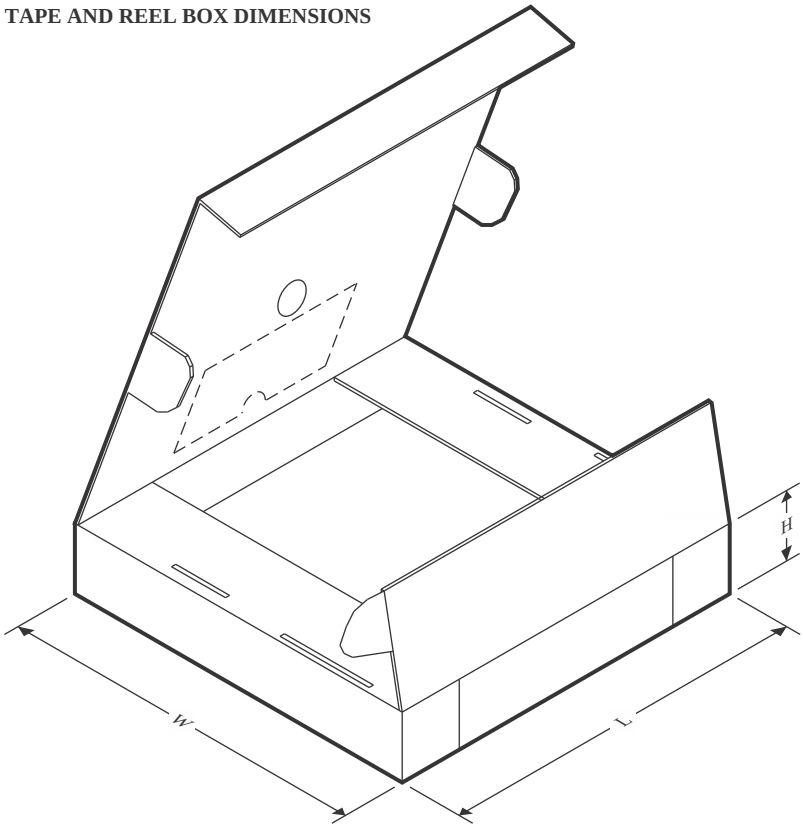
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC257ABQBR	WQFN	BQB	16	3000	180.0	12.4	2.8	3.8	1.2	4.0	12.0	Q1
SN74LVC257ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LVC257ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LVC257ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LVC257APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC257APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC257APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC257ARGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

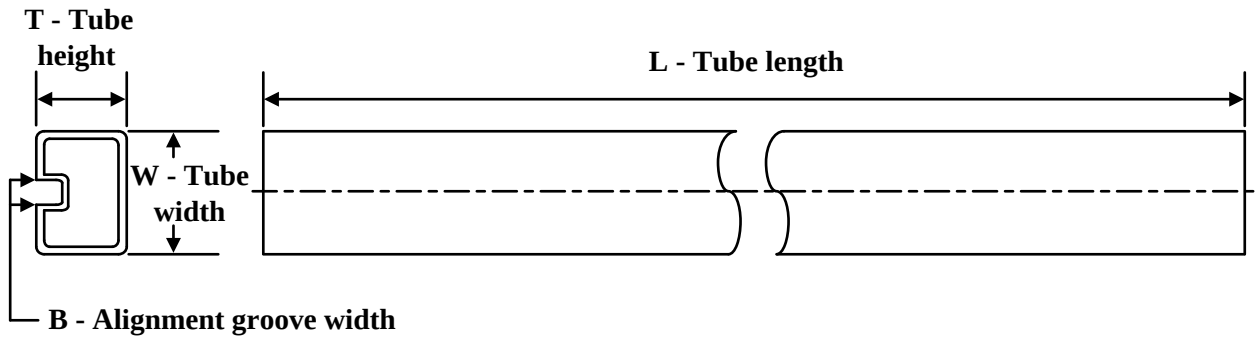
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC257ABQBR	WQFN	BQB	16	3000	210.0	185.0	35.0
SN74LVC257ADBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74LVC257ADR	SOIC	D	16	2500	353.0	353.0	32.0
SN74LVC257ANSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74LVC257APWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LVC257APWRG4	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LVC257APWT	TSSOP	PW	16	250	353.0	353.0	32.0
SN74LVC257ARGYR	VQFN	RGY	16	3000	353.0	353.0	32.0

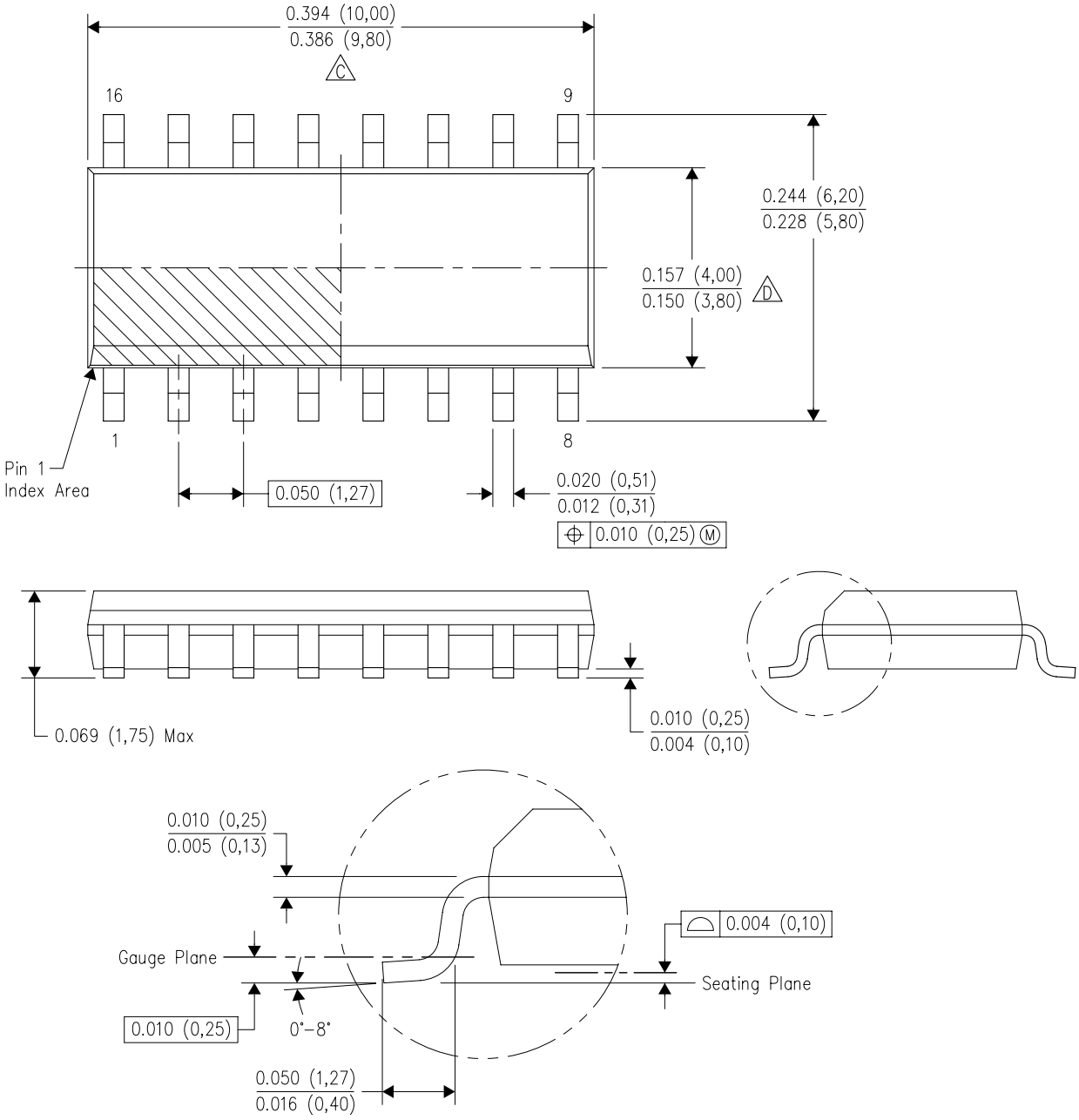
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-0050901QFA	W	CFP	16	25	506.98	26.16	6220	NA
SN74LVC257AD	D	SOIC	16	40	507	8	3940	4.32
SN74LVC257AD.B	D	SOIC	16	40	507	8	3940	4.32
SN74LVC257APW	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74LVC257APW.B	PW	TSSOP	16	90	530	10.2	3600	3.5
SNJ54LVC257AW	W	CFP	16	25	506.98	26.16	6220	NA

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



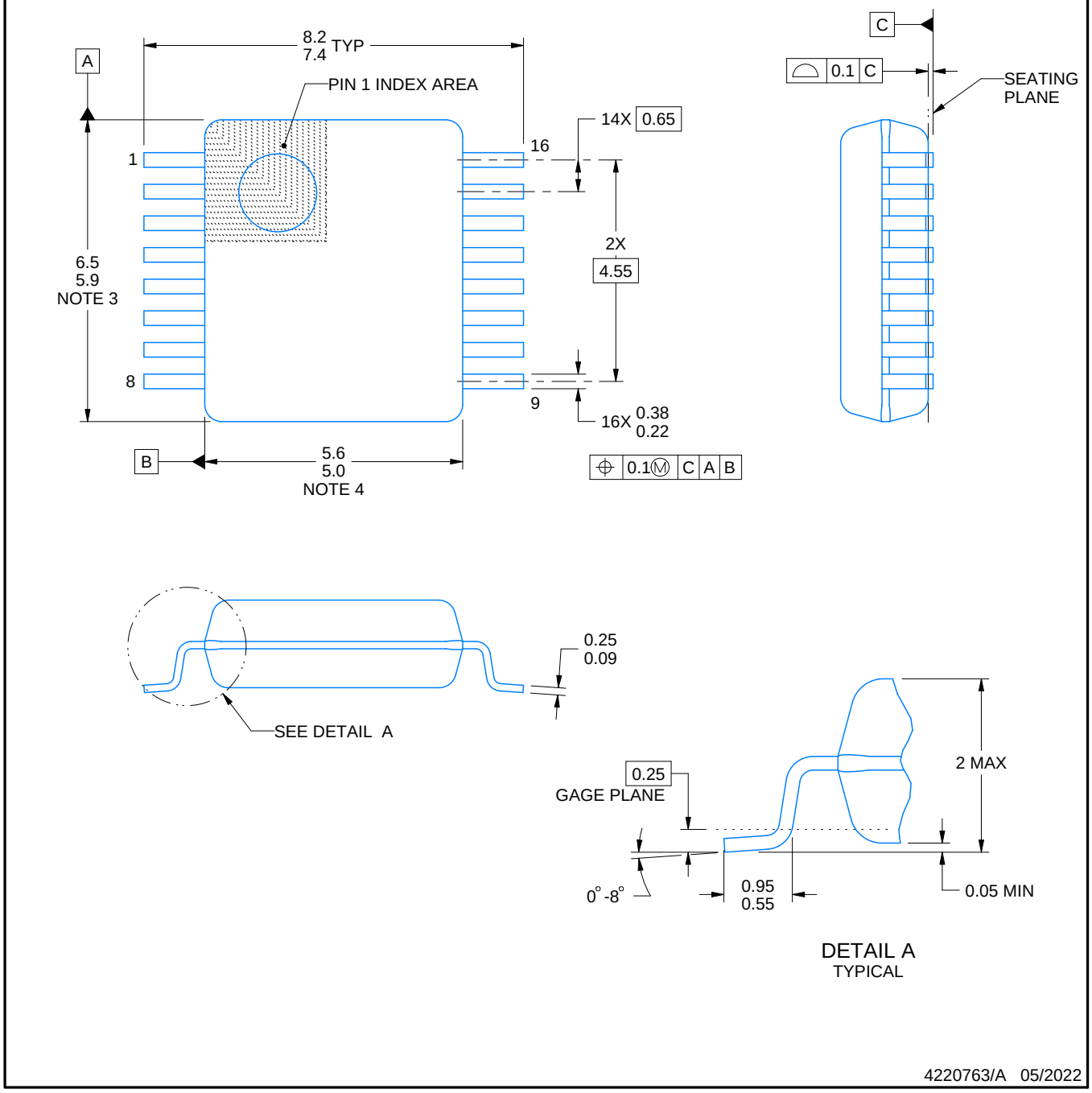
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

PACKAGE OUTLINE

DB0016A

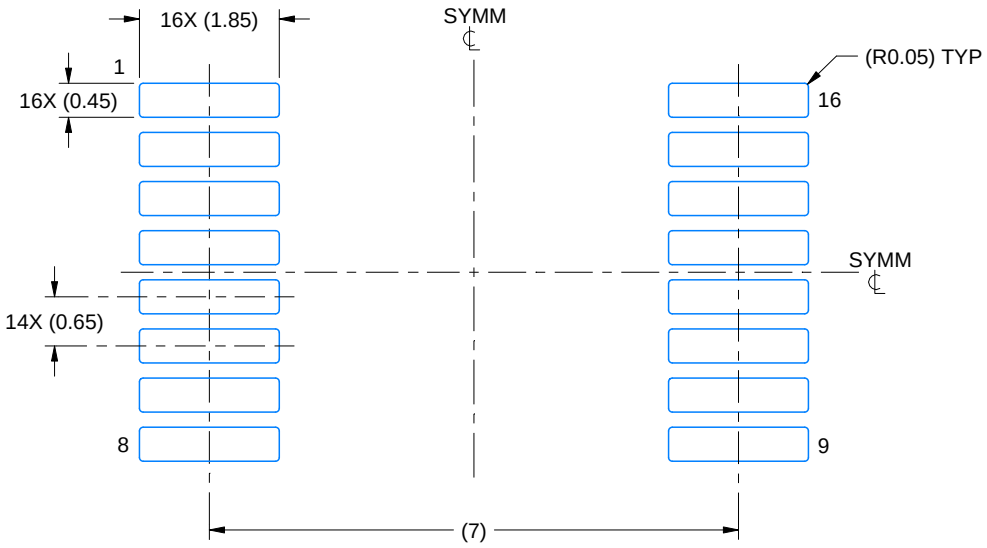
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

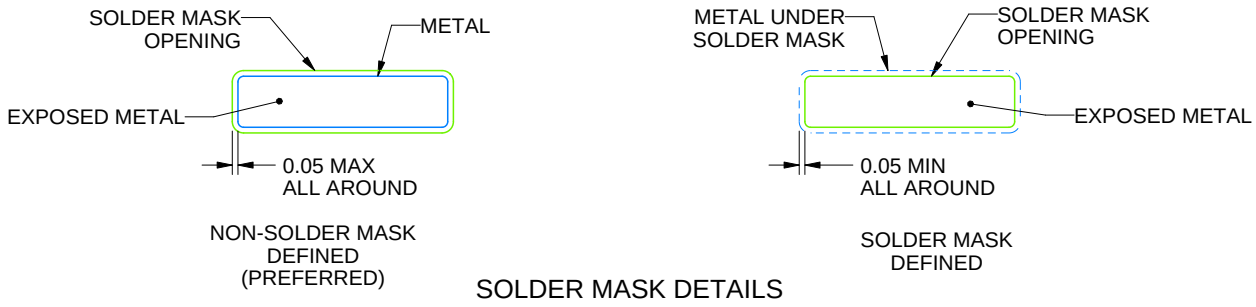


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

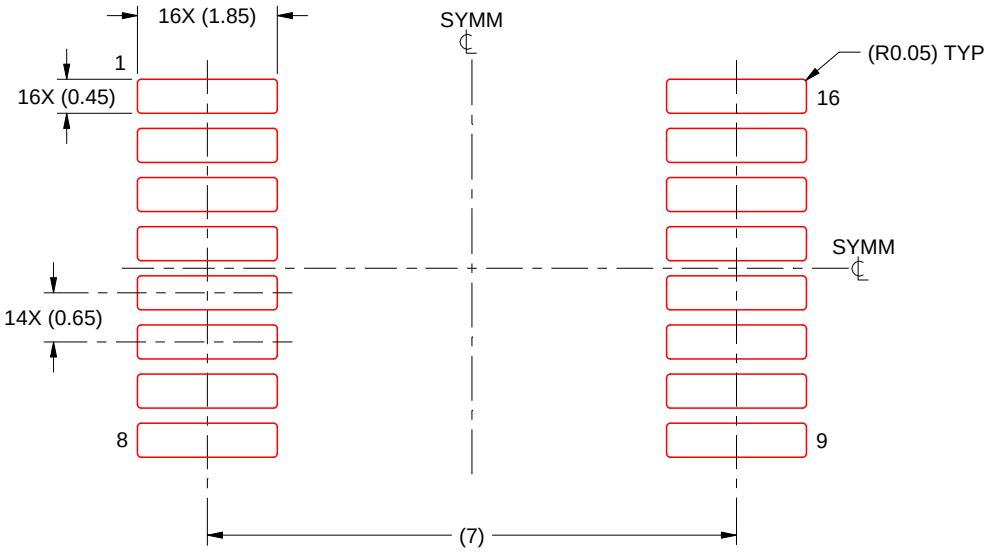


SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

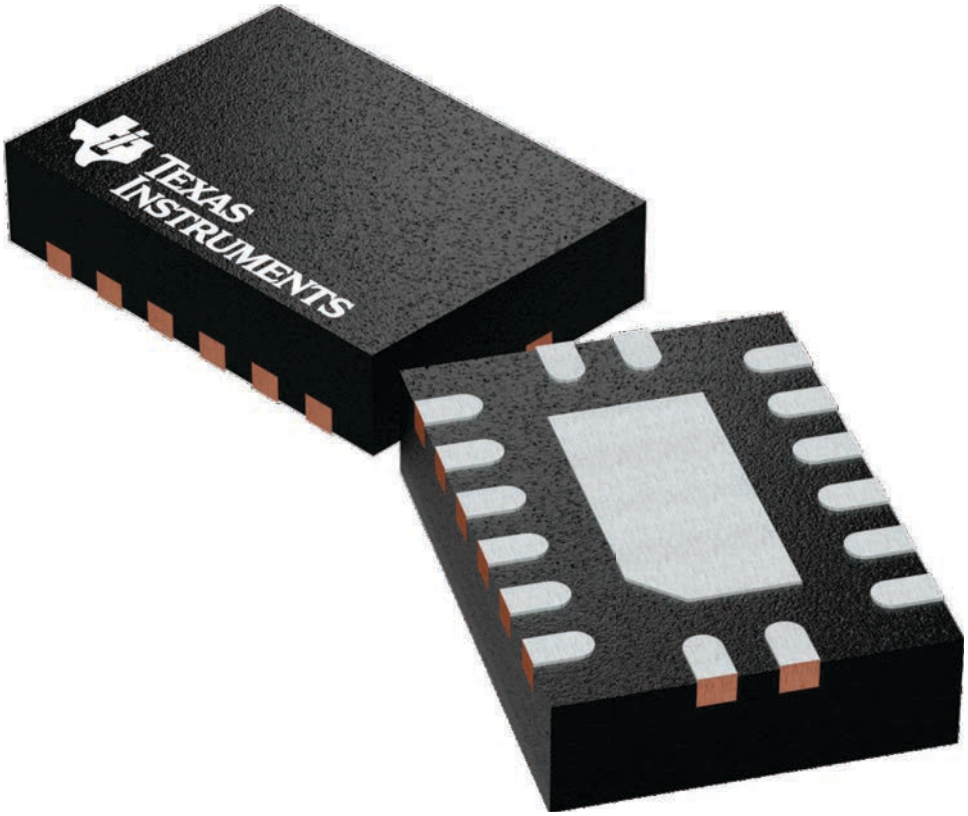
BQB 16

WQFN - 0.8 mm max height

2.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



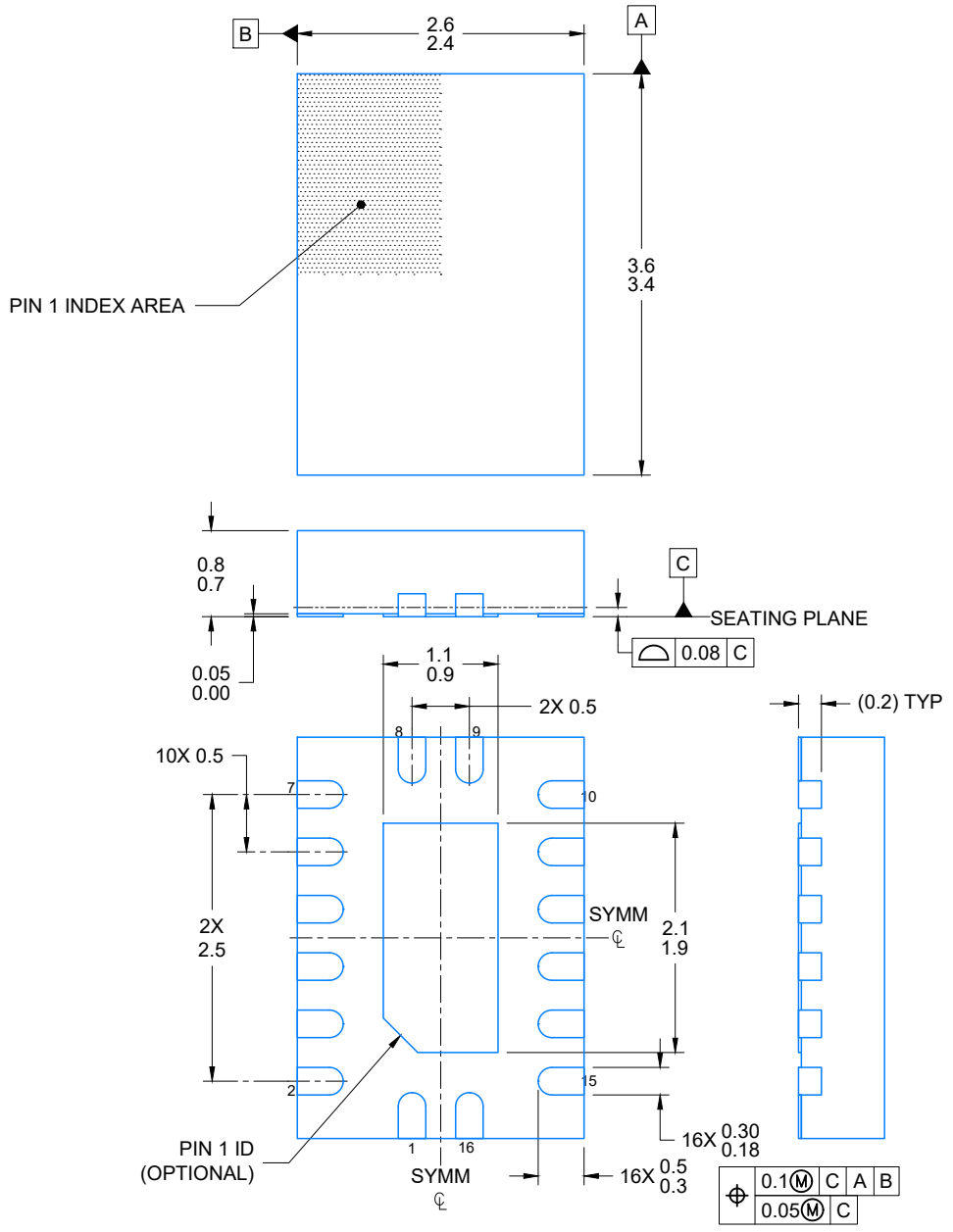
4226161/A

PACKAGE OUTLINE

BQB0016A

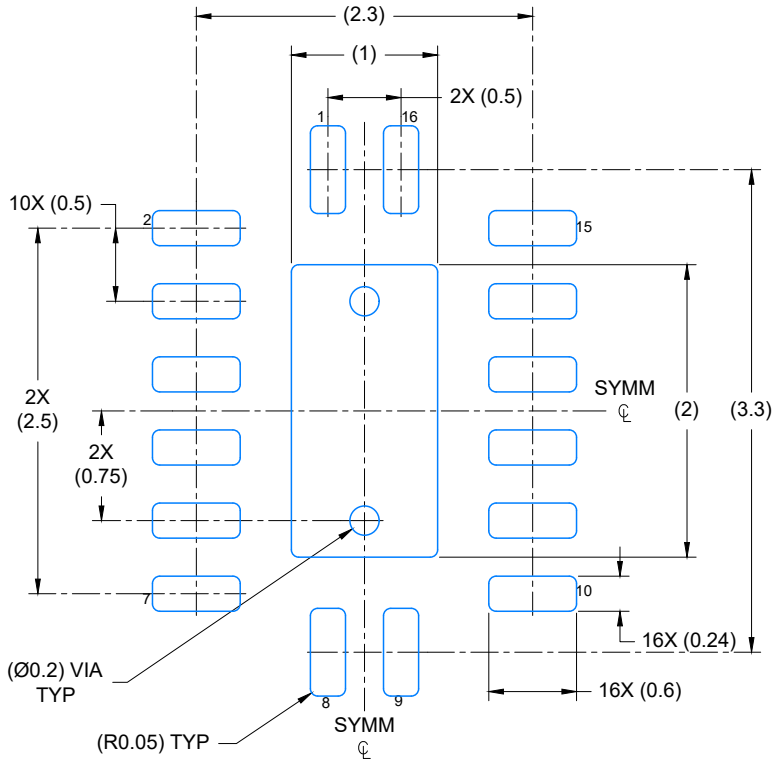
WQFN - 0.8 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD

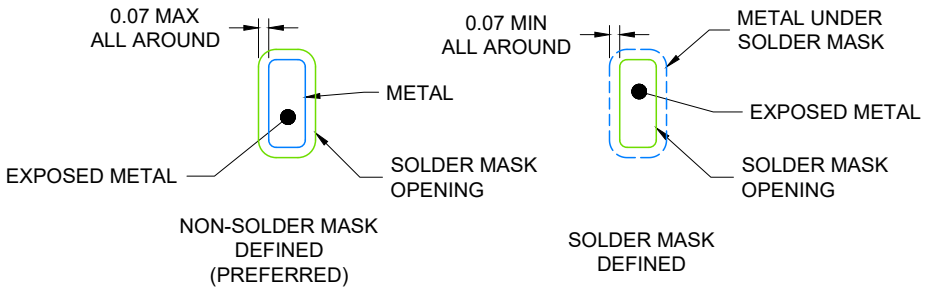


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



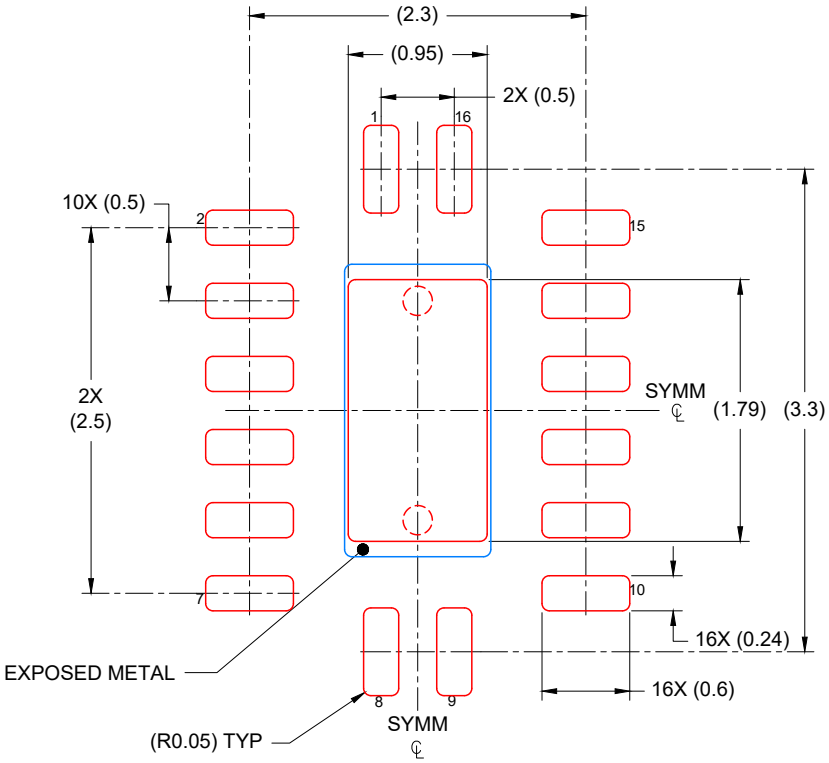
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



4224640/A 11/2018

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

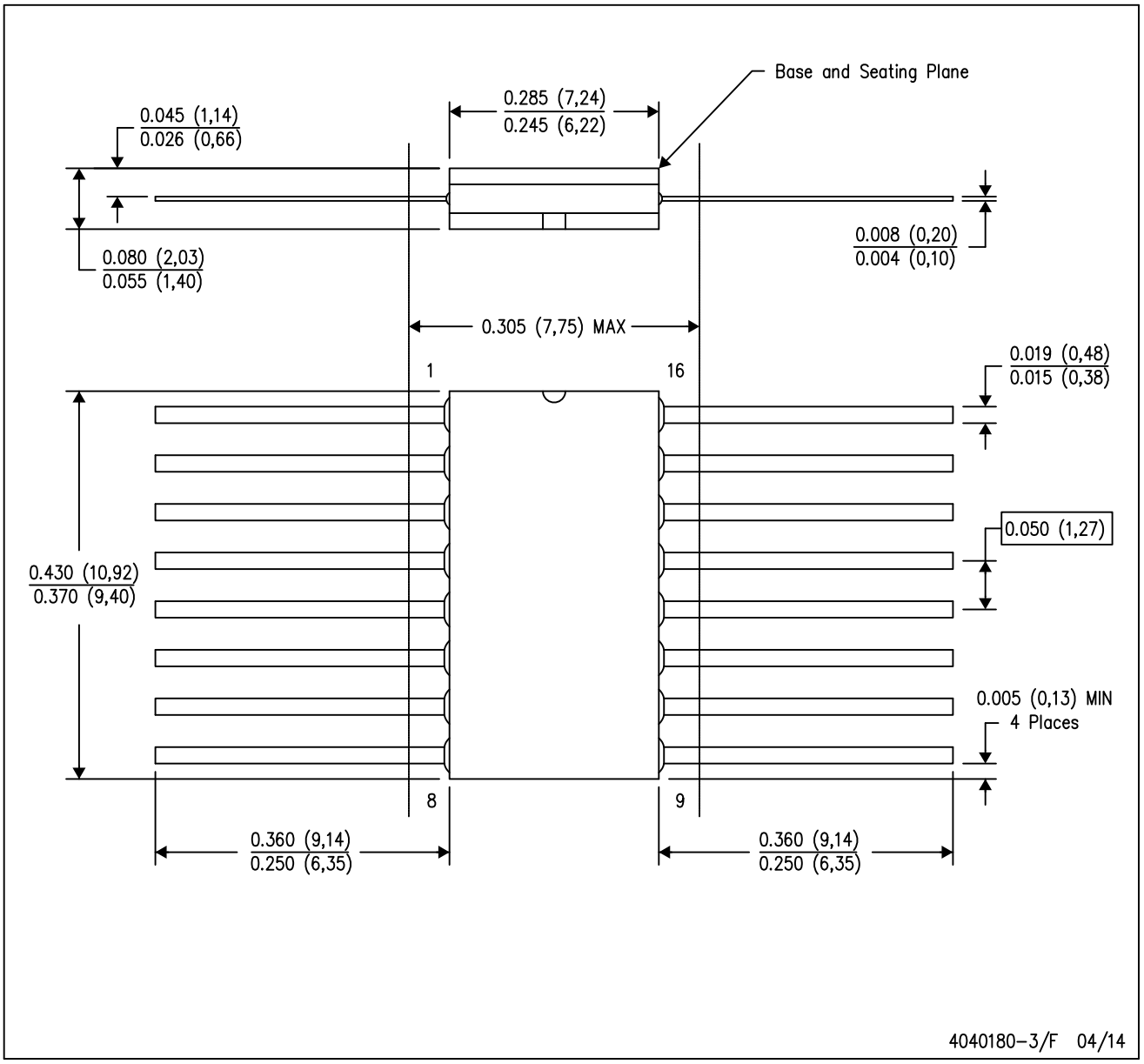
EXPOSED PAD
85% PRINTED COVERAGE BY AREA
SCALE: 20X

4224640/A 11/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

W (R–GDFP–F16) CERAMIC DUAL FLATPACK



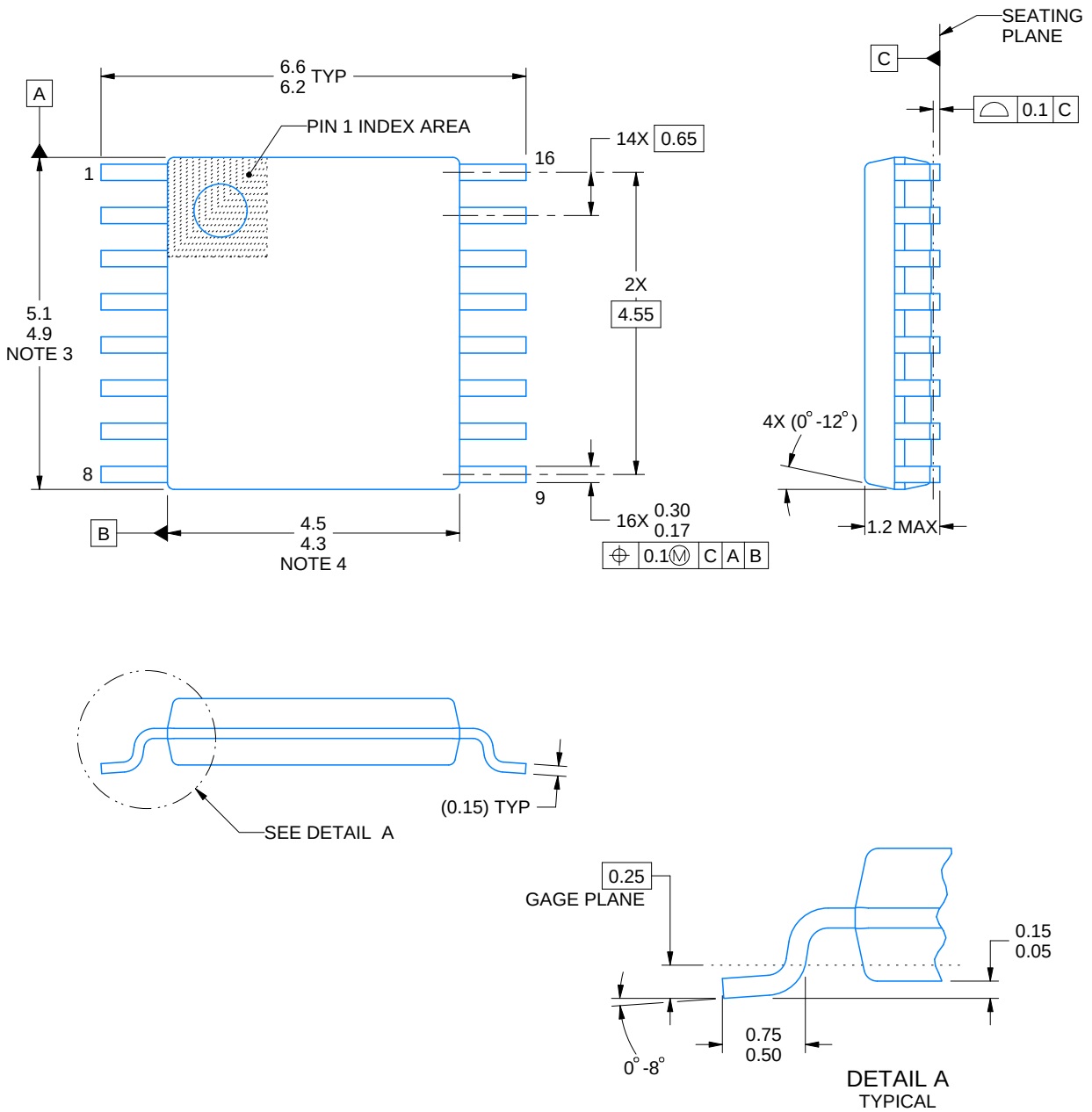
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

PACKAGE OUTLINE

PW0016A

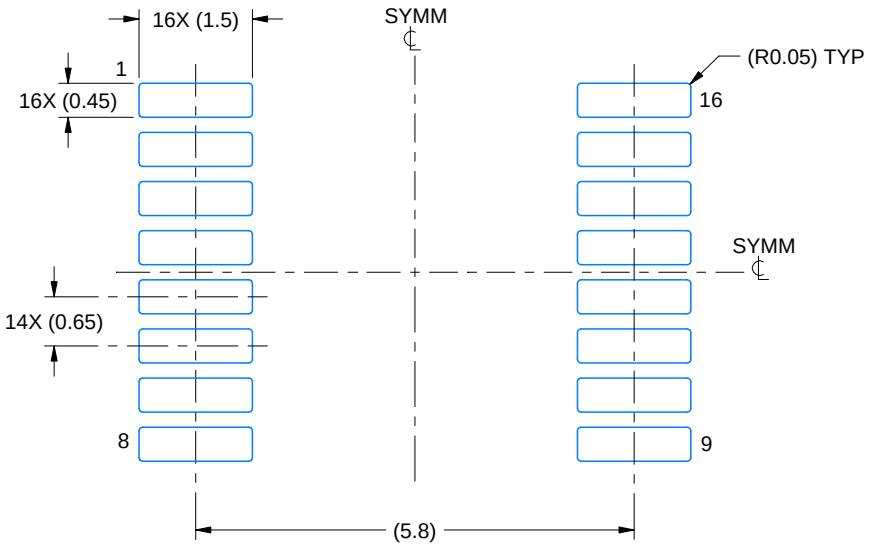
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



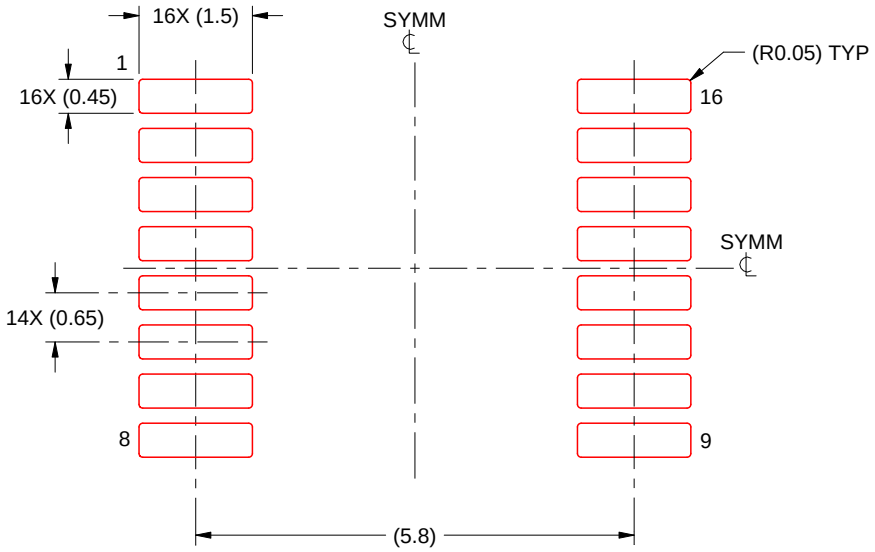
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



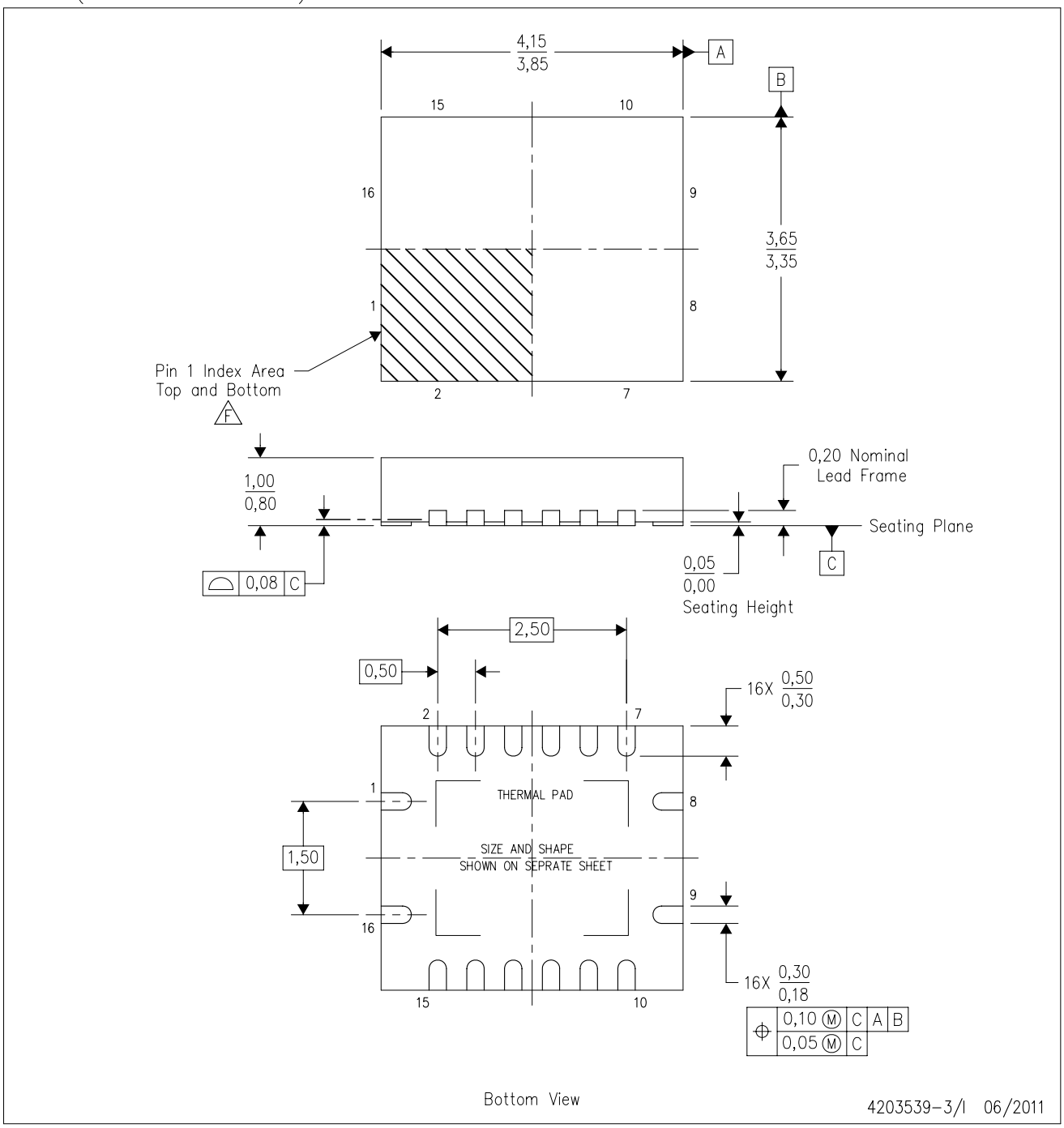
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
G. Package complies to JEDEC MO–241 variation BA.

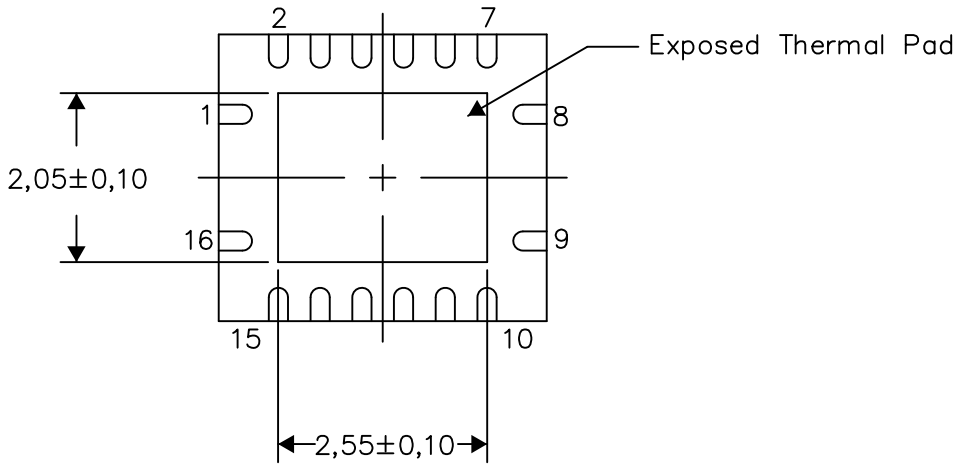
RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



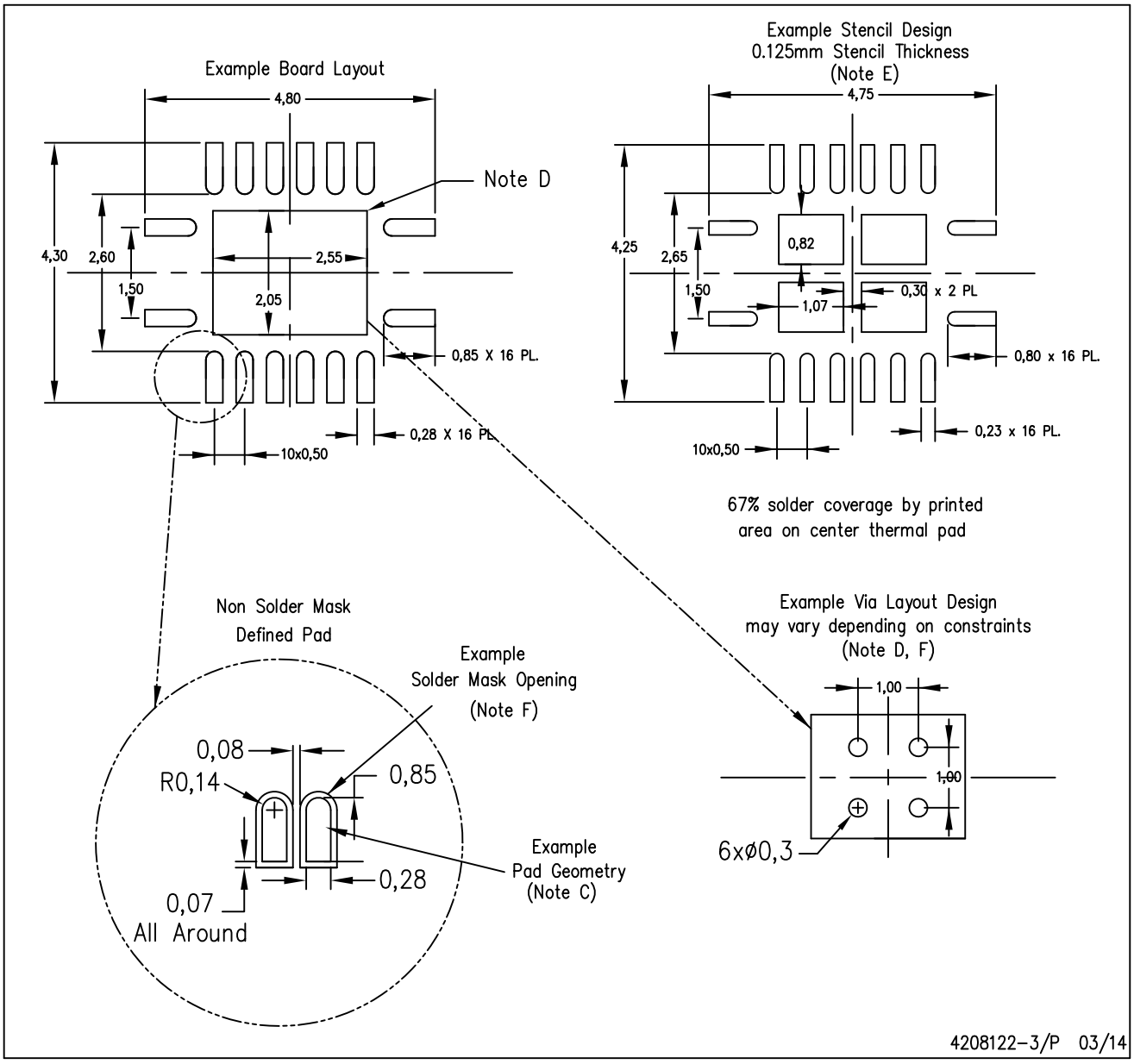
Bottom View

Exposed Thermal Pad Dimensions

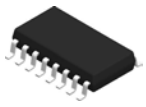
4206353–3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R–PVQFN–N16) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http: //www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

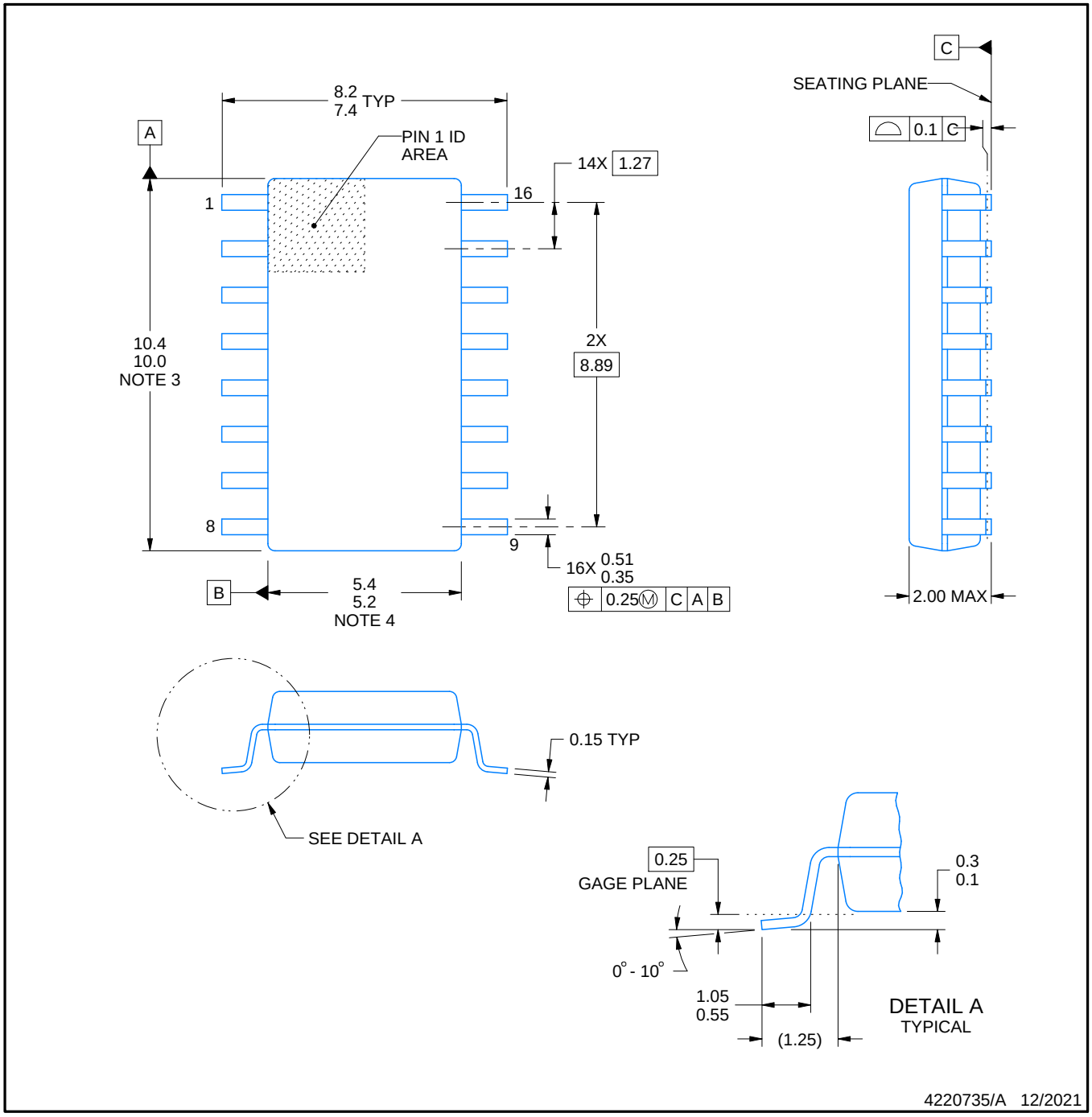


PACKAGE OUTLINE

NS0016A

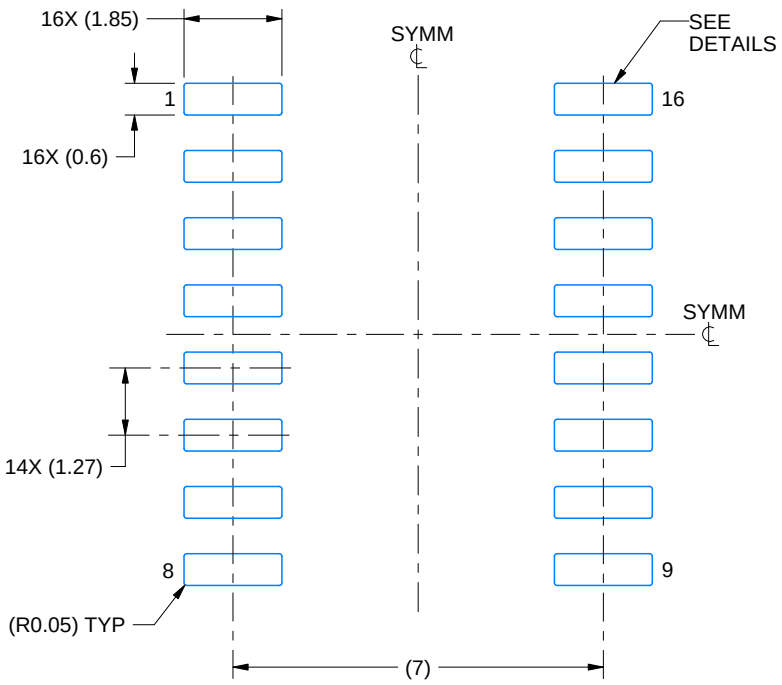
SOP - 2.00 mm max height

SOP

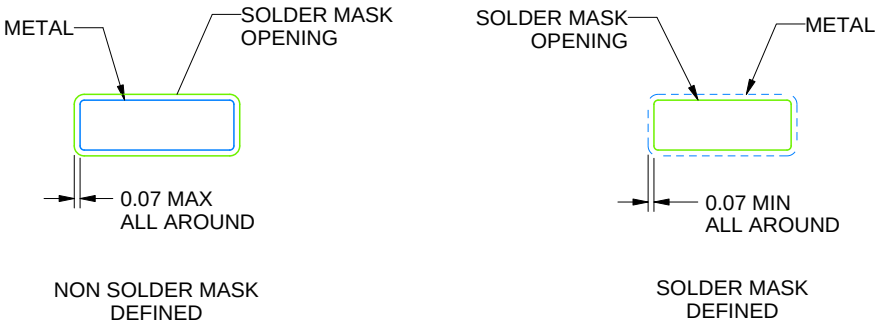


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

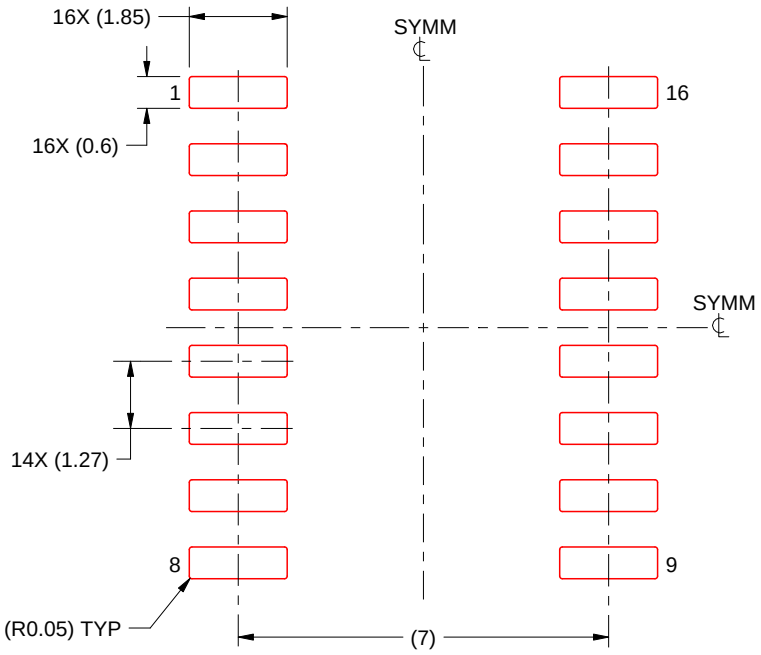
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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